



Better wettability and adhesion with PLASMACLEAN®

When removal of organic contamination or thin residual films in the ppm-range is required, PLASMACLEAN® processes are particularly suitable because of the high splitting properties of the gases. This includes precision cleaning (degreasing) of metal parts after milling, drilling, deep-drawing or punching, or the cleaning of electrical contacts e.g. prior to bonding. Other applications are the final cleaning of optical glasses, the removal of mould release agents and photo-resistant varnishes as well as the cleaning of bonding components, ceramic materials or textiles. Strict process control mechanism assure quality, reproducibility and easy handling with the plasma equipment.

PLASMA ELECTRONIC GmbH provides the Low-Pressure-Plasma equipment like the standard units *Piccolo* and *Domino* to apply this process at low temperature, accurately, cleanly and cheaply to a wide variety of substrates - regardless of the substrate geometry.



Specifications: PLASMACLEAN®	
Process type:	Plasma cleaning/degreasing
Typical cleaning rate:	10 nm/min.
Dispers energy:	50 mN/m
Optical properties:	No change
Surface modification:	No modification of substrate
Process temperature:	25°C to 80°C
Substrate:	Metals, glasses, ceramics, quartz, ...

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